

wherein said wires are signal wires excluding power supply wires, and
said wire dummies are further provided in areas overlapping positions of said power supply
wires that are provided in the first layer.

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5. (AMENDED) A semiconductor integrated circuit, comprising:
a plurality of layers provided on a semiconductor substrate;
wires provided in a first layer that is one of said plurality of layers; and
wire dummies provided in a second layer different from the first layer and having an
arrangement that avoids areas overlapping positions of said wires,
wherein said wires are signal wires excluding power supply wires, ✓
said wire dummies are further provided in areas overlapping positions of said power supply
wires that are provided in the first layer, and
said signal wires have a width less than a predetermined wire width, and said power supply
wires have a width greater than the predetermined wire width.

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8. (AMENDED) A semiconductor integrated circuit, comprising:
a wire layer;
wires provided in said wire layer; and
dummy patterns provided in said wire layer and having different sizes,
wherein said dummy patterns having different sizes are arranged at respective different
pattern intervals.